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Object of Declaration: MIC4609 Evaluation Board

EU Declaration of Conformity

Manufacturer:

Microchip Technology Inc. 2355 W. Chandler Blvd.

Chandler, Arizona, 85224-6199

USA

This declaration of conformity is issued by the manufacturer.

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12-Sep-14 Date

Signed for and on behalf of Microchip Technology Inc. at Chandler, Arizona, USA

Derek Carlson

VP Development Tools

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Preface

NOTICE TO CUSTOMERS

All documentation becomes dated, and this manual is no exception. Microchip tools and documentation are constantly evolving to meet customer needs, so some actual dialogs and/or tool descriptions may differ from those in this document. Please refer to our website (www.microchip.com) to obtain the latest documentation available.

Documents are identified with a "DS" number. This number is located on the bottom of each page, in front of the page number. The numbering convention for the DS number is "DSXXXXXXXXA", where "XXXXXXXX" is the document number and "A" is the revision level of the document.

For the most up-to-date information on development tools, see the MPLAB[®] IDE online help. Select the Help menu, and then Topics to open a list of available online help files.

INTRODUCTION

This chapter contains general information that will be useful to know before using the MIC4609 Evaluation Board. Items discussed in this chapter include:

- Document Layout
- · Conventions Used in This Guide
- Recommended Reading
- The Microchip Web Site
- · Customer Support
- · Revision History

DOCUMENT LAYOUT

This document describes how to install the MIC4609 Evaluation Board. It also describes how to operate the Evaluation Board. The manual layout is as follows:

- Chapter 1. "Product Overview" Important information about the MIC4609 Evaluation Board.
- Chapter 2. "Installation and Operation" Includes instructions on how to get started with the MIC4609 Evaluation Board.
- Appendix A. "Schematic and Layouts" Shows the schematic and layout diagrams for the MIC4609 Evaluation Board.
- Appendix B. "Bill of Materials (BOM)" Lists the parts used to build the MIC4609 Evaluation Board.

CONVENTIONS USED IN THIS GUIDE

This manual uses the following documentation conventions:

DOCUMENTATION CONVENTIONS

| Description | Represents | Examples |
|--|---|--|
| Arial font: | | <u> </u> |
| Italic characters | Referenced books | MPLAB [®] IDE User's Guide |
| | Emphasized text | is the only compiler |
| Initial caps | A window | the Output window |
| | A dialog | the Settings dialog |
| | A menu selection | select Enable Programmer |
| Quotes | A field name in a window or dialog | "Save project before build" |
| Underlined, Italic text with right angle bracket | A menu path | <u>File>Save</u> |
| Bold characters | A dialog button | Click OK |
| A tab | | Click the Power tab |
| N'Rnnnn | A number in verilog format, where N is the total number of digits, R is the radix and n is a digit. | 4'b0010, 2'hF1 |
| Text in angle brackets < > | A key on the keyboard | Press <enter>, <f1></f1></enter> |
| Courier New font: | | |
| Plain Courier New | Sample source code | #define START |
| | Filenames | autoexec.bat |
| | File paths | c:\mcc18\h |
| | Keywords | _asm, _endasm, static |
| | Command-line options | -Opa+, -Opa- |
| | Bit values | 0, 1 |
| | Constants | 0xff, 'A' |
| Italic Courier New | A variable argument | file.o, where file can be any valid filename |
| Square brackets [] | Optional arguments | mcc18 [options] file [options] |
| Curly brackets and pipe character: { } | Choice of mutually exclusive arguments; an OR selection | errorlevel {0 1} |
| Ellipses | Replaces repeated text | <pre>var_name [, var_name]</pre> |
| | Represents code supplied by user | <pre>void main (void) { }</pre> |

RECOMMENDED READING

This user's guide describes how to use MIC4609 Evaluation Board. Another useful document is listed below. The following Microchip document is available and recommended as supplemental reference resource:

• MIC4609 Data Sheet - "600V 3-Phase MOSFET/IGBT Driver" (DS20005531A)

THE MICROCHIP WEBSITE

Microchip provides online support via our website at www.microchip.com. This website is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the website contains the following information:

- Product Support Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip consultant program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives.

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Users of Microchip products can receive assistance through several channels:

- · Distributor or Representative
- · Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the website at: http://www.microchip.com/support.

REVISION HISTORY

Revision A (March 2016)

· Original release of this document.

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NOTES:



Chapter 1. Product Overview

1.1 INTRODUCTION

This chapter provides an overview of the MIC4609 Evaluation Board and covers the following topics:

- · MIC4609 Short Overview
- What is the MIC4609 Evaluation Board?
- MIC4609 Evaluation Board Kit Contents

1.2 MIC4609 SHORT OVERVIEW

The MIC4609 Evaluation Board is a 600V, 3-Phase driver that can be used with either IGBTs or MOSFETs. The MIC4609 features a 300 ns typical input filtering time to prevent unwanted pulses and a 550 ns of propagation delay. The board is available in an 28-pin wide SOIC package, with an operating junction temperature range of –40°C to +125°C.

1.3 WHAT IS THE MIC4609 EVALUATION BOARD?

The board is comprised of the MIC4609 3-phase driver, 6 IGBTs and provisions for current/voltage sensing. Right angle header J1 provides an interface to a controller board for input drive signals, control signals and V_{DD}/AV_{DD} supply voltages. The input drive signals may also be accessed with jumpers J2, J3, J5, J6, J10 and J11. TP4 and J16 are connected to the V_{DD} supply voltage. The high voltage V_{BUS} , power ground and the 3-phase motor connections are made through connector J9.

1.4 MIC4609 EVALUATION BOARD KIT CONTENTS

The MIC4609 Evaluation Board includes the following items:

- MIC4609 Evaluation Board (ADM00749)
- · Important Information Sheet

| MIC4609 Evaluation Board User's Guide | | | | | |
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Chapter 2. Installation and Operation

2.1 SYSTEM AND CONFIGURATION REQUIREMENTS

The MIC4609 Evaluation Board requires a V_{DD} power supply with an output between 10V and 20V, an AV $_{DD}$ supply of 3.3V or 5V and a high voltage V_{BUS} power supply that is used to driver the Motor or other load. Do not exceed 450V on V_{BUS} unless C17 is removed.

Note: The evaluation board does not have reverse polarity protection. Applying a negative voltage to the V_{BUS} (J16), VAV_{DD} (J1.12) or V_{DD} (J16 or J1.10) terminals may damage the device. Do not exceed 450V on V_{BUS} due to the 450V rating of the 10 μ F Aluminum Electrolytic capacitor (C17). Remove C17 if voltages between 450V and 600V are required.

2.2 CIRCUIT DESCRIPTION

The MIC4609 driver stage interfaces the incoming PWM signals to the IGBT power stage. Refer to the MIC4609 data sheet for detailed information on the driver's operation. Figure 2-1 is a partial schematic showing the components for phase A.

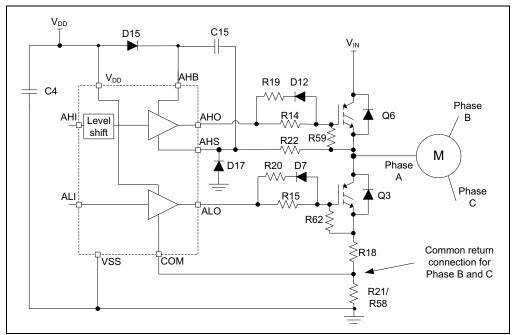


FIGURE 2-1: Phase A Circuitry

A resistor diode network is connected between the high and low-side driver output and the IGBT gate. Resistors R14 and R15 limit the driver output current into the gate, which slows down both the turn-on and turn-off of the IGBTs. The diode resistor combination in parallel with the series resistors (R19/D12 and R20/D7) allows the turn off to be faster than the turn-on.

Resistor R22 and diode D17 clamp the HS pin to prevent it from going too negative. This can occur when the high-side IGBT turns off and the motor current freewheels through the low-side IGBT (Q3).

Resistors R59 and R62 prevent charge from building up on the gates (and causing shoot-through current if both IGBTs turn-on) when V_{IN} is present but V_{DD} is not.

Current sense resistors in Phase A (R18) and Phase B (R35, not shown) provide a current signal to the controller for FOC or similar control architectures. Phase C does not have a sense resistor.

Parallel resistors R21 and R58 sense the current from all three phases and are used for overcurrent detection. The voltage across these resistors is sensed by the OC circuitry in the MIC4609, which shuts off the driver outputs if the OC threshold is exceeded.

2.2.1 Overcurrent and Fault circuitry

The MIC4609 can detect an overcurrent condition by sensing the voltage across a current sense resistor (R21/R58) and comparing it to an internal reference. If the peak voltage sensed exceeds the reference, the output drivers are turned off for a period of time before being allowed to turn back on. The delay is set with capacitor C31. Refer to the MIC4609 data sheet for additional information on setting the delay.

The FAULT pin goes low during the overcurrent event. This signal can be read by the controller to indicate a fault condition. The FAULT pin is pulled up to AV_{DD} with a 100 k Ω resistor. The fault signal can be monitored on TP1 or on pin 7 of jumper J1.

2.2.2 Enable Pin (EN)

A 3-pin header (J8) connected to the enable pin allows it to be set high (ON) or low (OFF). When the jumper is set high, it is pulled up to AV_{DD} through a 1 k Ω resistor. The signal is connected to pin 9 of J1. A high level on the EN pin turns ON the internal bias' in the driver and allows the driver to operate normally. Setting the EN pin low puts the device into a low IQ state and turns off all six driver outputs.

An external connection may be used to set the EN pin state. When using an external connection, make sure the EN pin voltage does not exceed V_{DD}.

2.2.3 Input Pins (xHI/xLI)

Connections to the six input pins are made through connector J1 (pins 1-6) or through individual headers (J2, J3, J5, J6, J10, and J11). The individual headers can be used to monitor the signals or to set them high or low.

Resistors in series with the inputs (as well as the EN and FAULT pins) can be used to limit current back to the controller if there is a fault condition or reverse voltage connection.

2.2.4 Power and Motor connections

There are four voltage dividers on the board that provide sensing feedback to the controller:

- VBUS SNS monitors the high voltage BUS
- FB_PHA, FB_PHB and FB_PHC monitor the phase voltages.

RECN is the reconstructed neutral voltage. These signals are filtered and clamped to ${\sf AV}_{\sf DD}$ for noise and surge overvoltage protection.

Installation and Operation

The sense voltage is the output of the voltage dividers and can be calculated using the following equation:

EQUATION 2-1:

$$VFB_PHA = V_{PhaseA} \times \left(\frac{R41}{R41 + R44 + R48}\right)$$

Similar calculations are made for Phases B, C and the V_{BUS} sense.

The resistor values on the board generate a 2V FB signal for a 300V BUS or phase voltage. If higher or lower voltage motors are used, the resistor divider values must be recalculated.

2.2.5 Power Stage and Motor connections

The V_{BUS} and power GND connections as well as the three motor phase connections are accessed through connector J9. In the existing evaluation board configuration, the maximum voltage on V_{BUS} is 450V DC. This is limited by the voltage rating of the electrolytic capacitor, C17. If the capacitor is removed, V_{BUS} can increase to 600V.

Locations for an RC snubber for each of the phase nodes are located on the back of the board. These are not populated but are available to attenuate ringing if necessary.

| MIC4609 Evaluation Board User's Guide | | | | | | |
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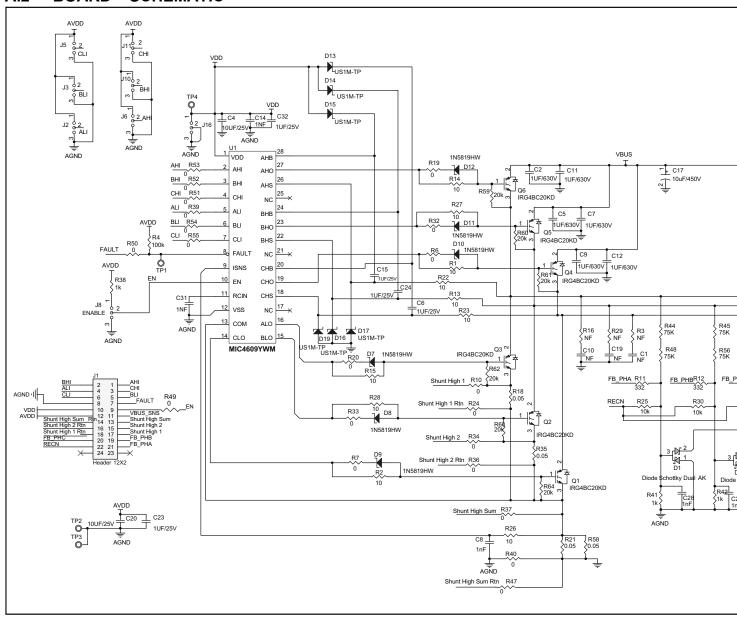
Appendix A. Schematic and Layouts

A.1 INTRODUCTION

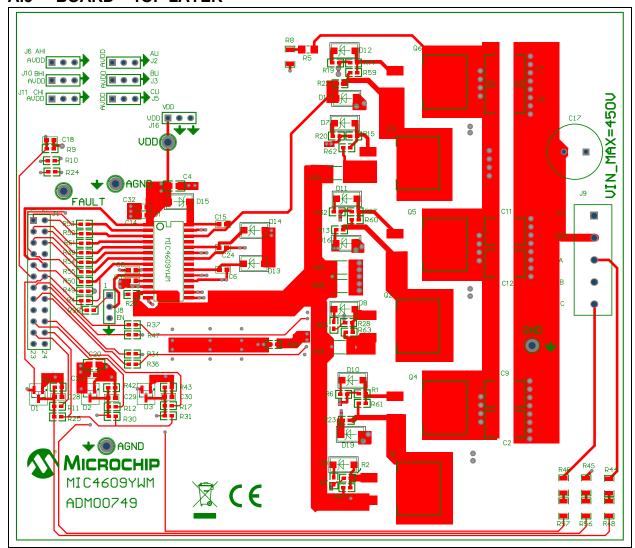
This appendix contains the following schematics and layouts for the MIC4609 Evaluation Board:

- Board Schematic
- Board Top Layer
- Board Top Copper
- Board Mid Layer 1
- Board Mid Layer 2
- Board Bottom Copper
- · Board Bottom Layer

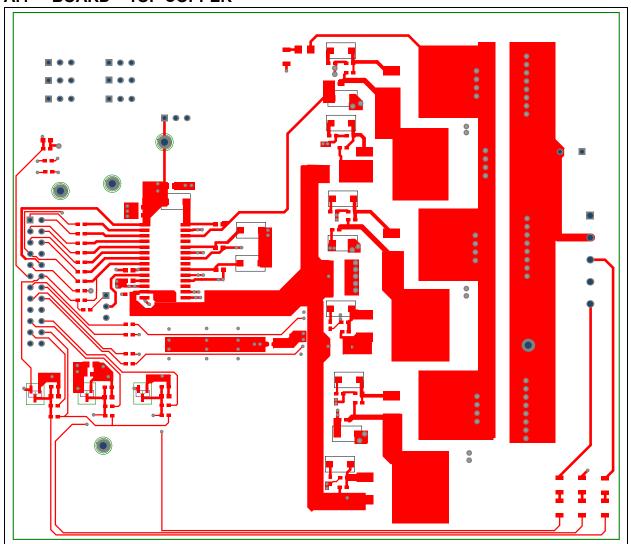




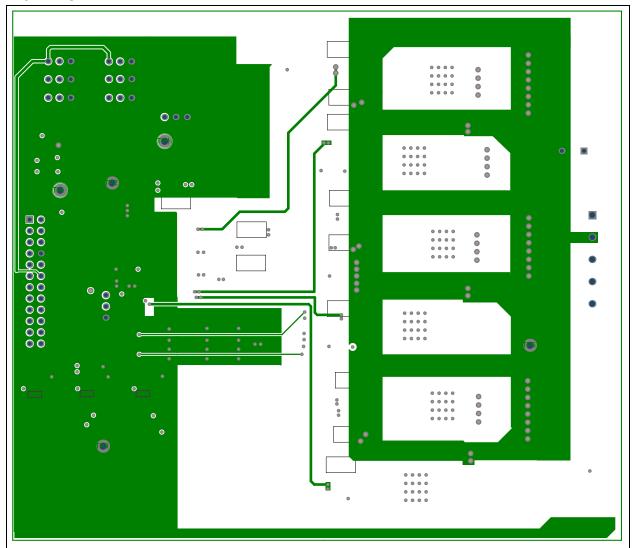
A.3 BOARD - TOP LAYER



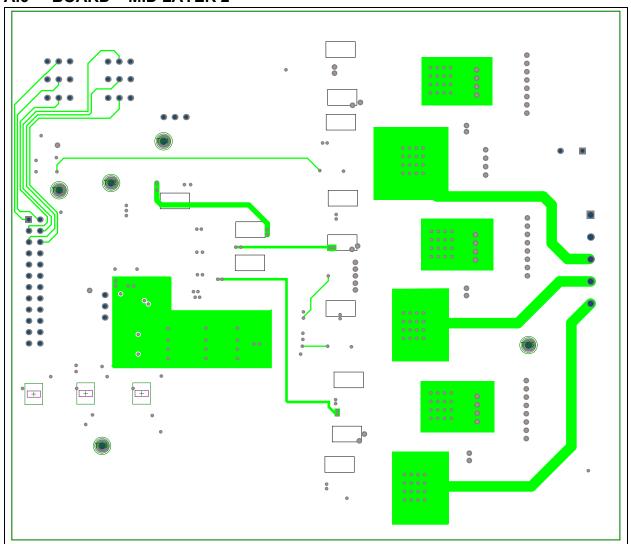
A.4 BOARD - TOP COPPER



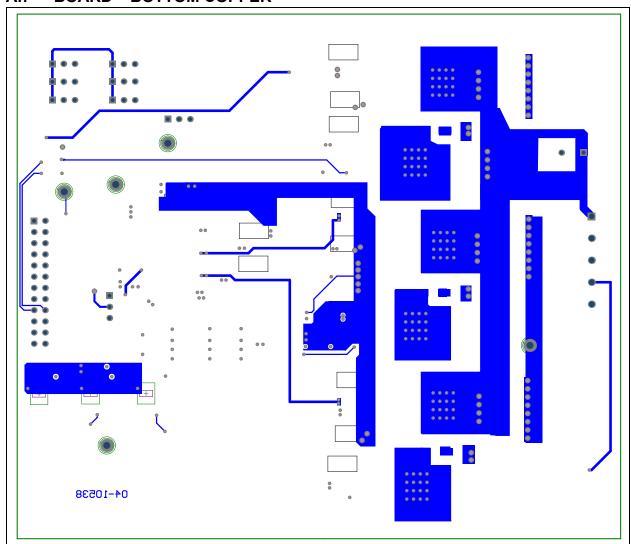
A.5 BOARD - MID LAYER 1



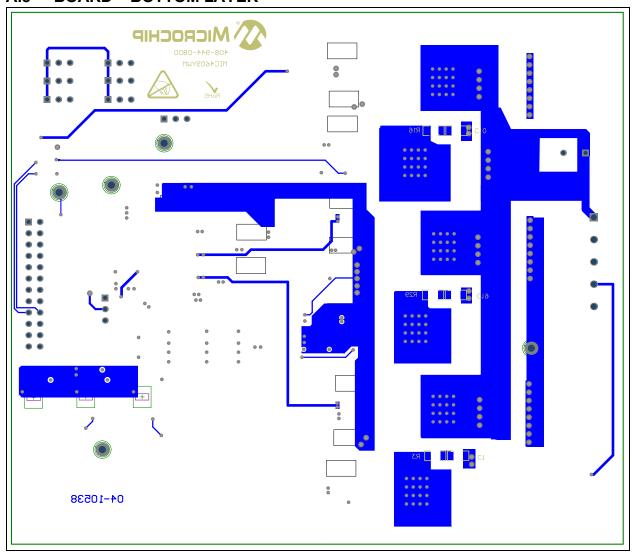
A.6 BOARD - MID LAYER 2



A.7 BOARD - BOTTOM COPPER



A.8 BOARD - BOTTOM LAYER





Appendix B. Bill of Materials (BOM)

TABLE B-1: BILL OF MATERIALS (BOM)

| Qty. | Reference | Description | Manufacturer | Part Number |
|------|---|-------------------------------------|-------------------------------|----------------------|
| 3 | C1, C10, C19 | 1206 size capacitor DO NOT POPULATE | | |
| 6 | C2, C5, C7, C9, C11, C12 | 1 μF/630V | TDK Corporation | CKG57NX7T2J105M500JH |
| 2 | C4, C20 | 10 μF/25V | TDK Corporation | C2012X5R1E106K085AC |
| 5 | C6, C15, C23, C24, C32 | 1 μF/25V | TDK Corporation | C1608X7R1E105K080AB |
| 7 | C8, C14, C18, C28, C29, C30, C31 | 1nF/50V | TDK Corporation | C1608X7R1H102K080AE |
| 1 | C17 | 10 μF/450V Al. El | Panasonic® - ECG | EEU-EE2W100 |
| 1 | U1 | 600V, 3-phase driver | Microchip Technology, Inc. | MIC4609YWM |
| 3 | R3, R16, R29 | 1206 size resistor DO NOT POPULATE | | |
| 1 | R4 | 100K, 1%, 1/4W | Panasonic- ECG | ERJ-3EKF1003V |
| 10 | R1, R2, R13, R14, R15, R22, R23, R26, R27, R28 | 10, 1%, 1/10W | Panasonic- ECG | ERJ-3EKF10R0V |
| 5 | 'R9, R38, R41, R42, R43 | 1k, 1%, 1/10W | Panasonic- ECG | ERJ-3EKF1001V |
| 3 | R25, R30, R31 | 10K, 1%, 1/10W | Panasonic- ECG | ERJ-3EKF1002V |
| 8 | R5, R8, R44, R45, R46, R48, R56, R57 | 75K, 1%, 1/4W | Panasonic- ECG | ERJ-8ENF7502V |
| 21 | R6, R7, R10, R19, R20, R24, R32, R33, R34, R36, R37, R39, R40, R47, R49, R50, R51, R52, R53, R54, R55 | 0, 1%, 1/10W | Panasonic- ECG | ERJ-3GEY0R00V |
| 3 | R11, R12, R17 | 332Ω,1%, 1/10W | Panasonic- ECG | ERJ-3EKF3320V |
| 4 | R18, R21, R35, R58 | 0.05Ω, 1W 1% | Panasonic- ECG | ERJ-M1WSF50MU |
| 6 | R59, R60, R61, R62, R63, R64 | 20K, 1%, 1/10W | Panasonic- ECG | ERJ-3EKF2002V |

Note 1: The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.

TABLE B-2: BILL OF MATERIALS (BOM) - MECHANICAL PARTS

| Qty | Reference | Description | Manufacturer | Part Number |
|-----|--------------------------------------|---------------------------------------|---------------------------|--------------|
| 3 | D1, D2, D3 | Diode Schottky Dual AK 40V/200mA | Diodes Incorporated® | BAS40-04 |
| 6 | D7, D8, D9, D10, D11, D12 | Schottky, 1A/40V | Diodes Incorporated | 1N5819HW |
| 6 | D13, D14, D15, D16, D17, D19 | 100V/1A Ultra fast diode | Diodes Incorporated | US1M-TP |
| 1 | J1 | Header, 12-Pin, dual row, right angle | FCI | 68021-224HLF |
| 8 | J2, J3, J5, J6, J8, J10, J11, J16 | Header, 3-pin | FCI | 68000-103HLF |
| 1 | J9 | 5 position terminal block | On-Shore Technology, Inc. | ED2612 |
| 6 | Q1, Q2, Q3, Q4, | IGBT | Infineon Technologies AG | IRG4BC20KD |
| | Q5, Q6 (Note 2) | IGBT | Infineon Technologies AG | IKB06N60T |
| | | IGBT | Fairchild Semiconductor® | SGW10N60RUFD |
| | | IGBT | STMicroelectronics | STGB10NC60KD |

Note 1: The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.

^{2:} Note that only one set of six IGBTs are used at a time. You can choose the IGBT produced by one of the three listed manufacturers.

| Dili di Matchais (Ddivi | Bill | of | Materials (| (BOM) |
|-------------------------|------|----|-------------|-------|
|-------------------------|------|----|-------------|-------|

| NOTES: | | | |
|--------|--|--|--|
| | | | |



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